

2SK2151-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODU	CT SUMMARY		
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)
- 30	0.050 at V _{GS} = - 10 V	- 7.6	13 nC
- 30	0.056 at V _{GS} = - 4.5 V	- 6.0	13110

• 100 % R_g Tested

FEATURES

Definition

Pb-free



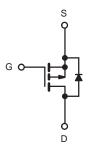
FREE

APPLICATIONS

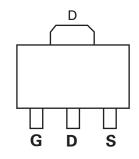
• Trench Power MOSFET

• Halogen-free According to IEC 61249-2-21

- Load Switch
- · Battery Switch







Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage	V _{GS}	± 20		
	T _C = 25 °C		- 7.6	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 5.8	
Continuous Diain Curient (1) = 130 °C)	T _A = 25 °C	l _D	- 6.0 ^{a, b}	
	T _A = 70 °C		- 5.2 ^{a, b}	Α
Pulsed Drain Current	I _{DM}	- 35		
0 " 0 0 0 0	T _C = 25 °C		- 3.5	
Continuous Source-Drain Diode Current	T _A = 25 °C	ls –	- 2.1 ^{a, b}	
	T _C = 25 °C		6.5	
Maximum Power Dissipation	T _C = 70 °C		3.5	14/
	T _A = 25 °C	P _D	2.5 ^{a, b}	W
	T _A = 70 °C		1.6 ^{a, b}	
Operating Junction and Storage Temperature Rang	T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	40	50	°C/W		
Maximum Junction-to-Foot	Steady State	R _{thJF}	24	30	C/VV		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 95 °C/W.
- d. Package limited.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 31		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1D = - 250 μΑ		4.5		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zoro Coto Voltago Droin Current	laaa	V _{DS} = - 30 V, V _{GS} = 0 V			- 1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 20			Α
David Course Co Otata Davids and	D	V _{GS} = - 10 V, I _D = - 7.0 A		0.050		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 5.6 A		0.056		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 7.0 A		18		S
Dynamic ^b						
Input Capacitance	pacitance C _{iss}			1355		
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		180		pF
Reverse Transfer Capacitance	C _{rss}			145		
Total Cata Charge	Q_g	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7.0 \text{ A}$		25	38	nC
Total Gate Charge				13	20	
Gate-Source Charge	Q_{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.0 \text{ A}$		3.5		
Gate-Drain Charge	Q_{gd}			5.5		
Gate Resistance	R _g	f = 1 MHz	0.4	2.0	4.0	Ω
Turn-On Delay Time	t _{d(on)}			10	20	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 2.7 \Omega$		13	20	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5.6 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		23	35]
Fall Time	t _f			9	18	
Turn-On Delay Time	t _{d(on)}			38	57	ns
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 2.7 \Omega$		89	134	1
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5.6 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		22	33	
Fall Time	t _f			11	17	
Drain-Source Body Diode Characteris	tics					
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 6.5	Α
Pulse Diode Forward Current	I _{SM}				- 30] ^
Body Diode Voltage	V _{SD}	I _S = - 5.6 A, V _{GS} = 0 V		- 0.71	- 1.2	V
Body Diode Reverse Recovery Time				22	33	ns
Body Diode Reverse Recovery Charge	Q_{rr}	L = 56 A dl/dt = 100 A/up T = 25 °C		17	26	nC
Reverse Recovery Fall Time	t _a	$I_F = -5.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		13		ns
Reverse Recovery Rise Time	t _b			9		

Notes:

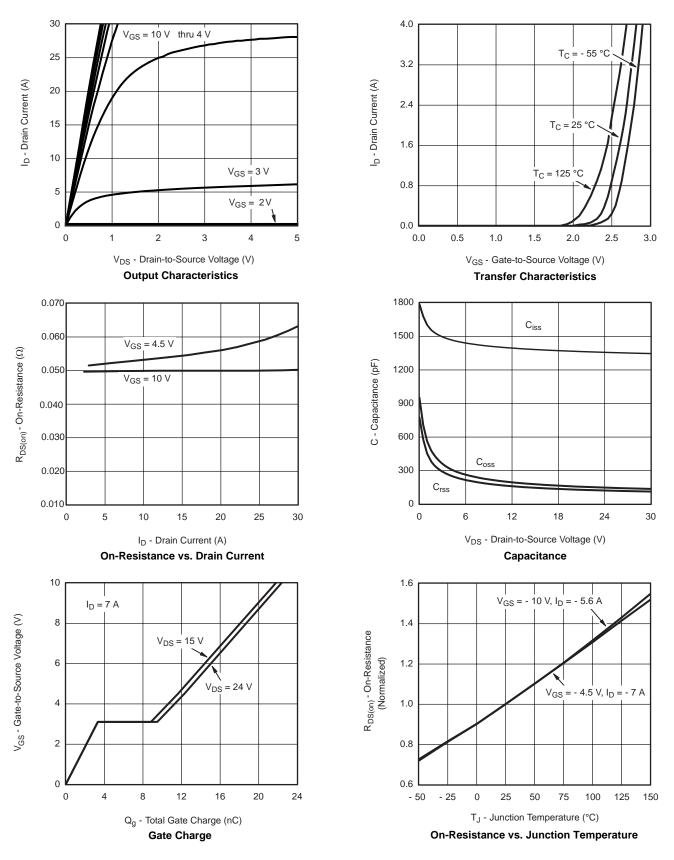
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

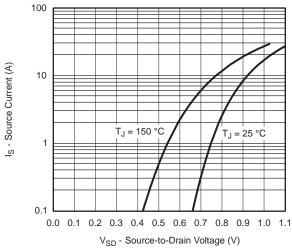
b. Guaranteed by design, not subject to production testing.



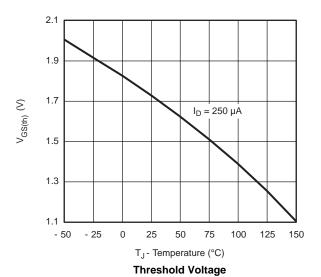


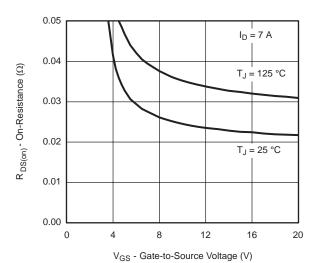
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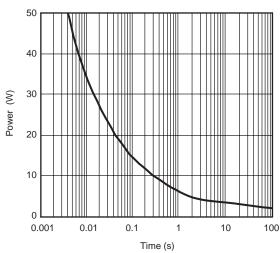


Source-Drain Diode Forward Voltage

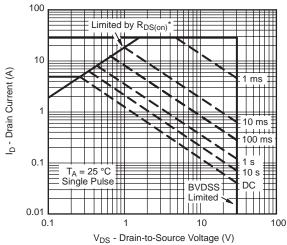




On-Resistance vs. Gate-to-Source Voltage



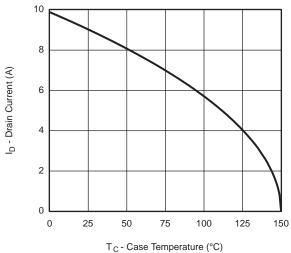
Single Pulse Power, Junction-to-Ambient



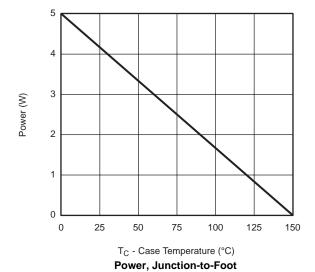
* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

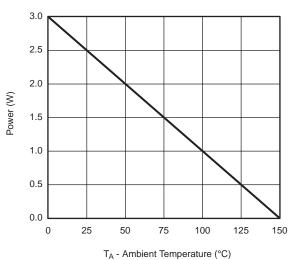
Safe Operating Area





Current Derating*



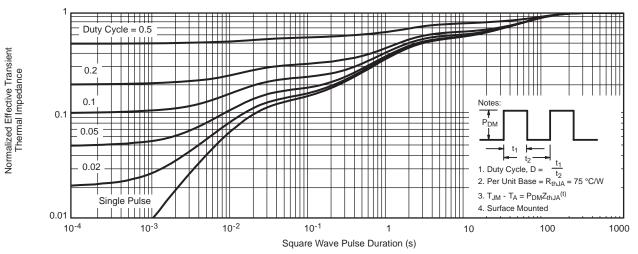


Power Derating, Junction-to-Ambient

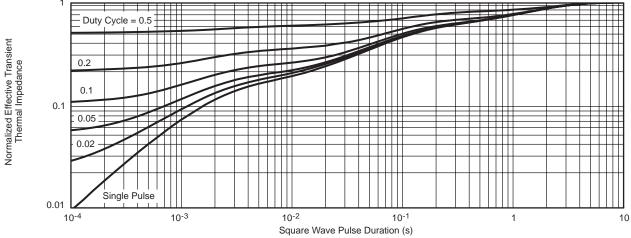
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^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package





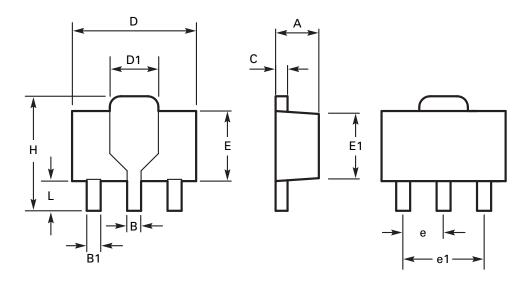
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



Package outline - SOT89



DIM	Millin	neters	Inc	hes	DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Мах
Α	1.40	1.60	0.550	0.630	Е	2.29	2.60	0.090	0.102
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	е	1.50 BSC		0.059 BSC	
С	0.35	0.44	0.014	0.017	e1	3.00 BSC		0.118 BSC	
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167
D1	1.62	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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